Title (en)

MICRO-ALLOYED OXYGEN-FREE COPPER ALLOY AND ITS USE

Title (de)

MIKROLEGIERTE SAUERSTOFFFREIE KUPFERLEGIERUNG UND IHRE VERWENDUNG

Title (fr)

ALLIAGE DE CUIVRE EXEMPT D'OXYGENE MICROALLIE ET UTILISATION DE CELUI-CI

Publication

EP 1373588 A1 20040102 (EN)

Application

EP 02703649 A 20020308

Priority

- FI 0200184 W 20020308
- FI 20010473 A 20010309

Abstract (en)

[origin: WO02072901A1] An oxygen-free copper alloy comprising oxygen-free copper and, micro-alloyed therein, about 1 250 ppm tin (Sn) and/or about 1 150 ppm manganese (Mn). The invention also relates to the use of said copper alloy.

IPC 1-7

C22C 9/00; H01B 1/02

IPC 8 full level

C22C 9/02 (2006.01); **C22C 9/05** (2006.01); **H01B 1/02** (2006.01)

CPC (source: EP US)

C22C 9/02 (2013.01 - EP US); **C22C 9/05** (2013.01 - EP US); **H01B 1/026** (2013.01 - EP US)

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)

WO 02072901 A1 20020919; BR 0207879 A 20040302; CN 1496416 A 20040512; CZ 20032372 A3 20031217; EP 1373588 A1 20040102; FI 113061 B 20040227; FI 20010473 A0 20010309; FI 20010473 A 20020910; HU P0303470 A2 20040128; HU P0303470 A3 20051028; JP 2004538362 A 20041224; PL 363969 A1 20041129; SK 11512003 A3 20040406; US 2004096353 A1 20040520

DOCDB simple family (application)

FI 0200184 W 20020308; BR 0207879 A 20020308; CN 02806243 A 20020308; CZ 20032372 A 20020308; EP 02703649 A 20020308; FI 20010473 A 20010309; HU P0303470 A 20020308; JP 2002571950 A 20020308; PL 36396902 A 20020308; SK 11512003 A 20020308; US 47119103 A 20030909